ESD Protection Diodes Silicon Epitaxial Planar

DF6F6.8MTU

1. Applications

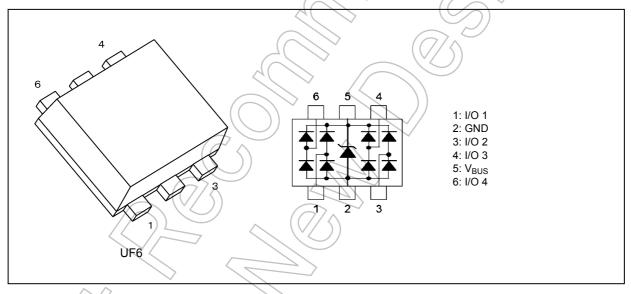
· ESD Protection

Note: This product is designed for protection against electrostatic discharge (ESD) and is not intended for any other purpose, including, but not limited to, voltage regulation.

2. Features

- (1) ESD protection for up to 4 high-speed data lines and 1 V_{BUS} line.
- (2) Ultra compact packaging for easy configuration in any ESD protection circuits.
- (3) Low Input/output-to-ground capacitance: $C_{t(1)} = 0.6 \text{ pF (typ.)}$.

3. Packaging and Internal Circuit



4. Absolute Maximum Ratings (Note) (Unless otherwise specified, T_a = 25 °C)

Characteristics	Symbol	Rating	Unit
Electrostatic discharge voltage (IEC61000-4-2)(Contact)	V _{ESD}	±8	kV
Junction temperature	Tj	150	°C
Storage temperature	T _{stg}	-55 to 150	°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).



5. Electrical Characteristics (Unless otherwise specified, Ta = 25 °C)

 $V_{\mbox{\scriptsize RWM}}$: Working peak reverse

voltage

V_{BR}: Reverse breakdown voltage I_{BR}: Reverse breakdown current

I_R: Reverse current
V_C: Clamp voltage
I_{PP}: Peak pulse current
R_{DYN}: Dynamic resistance
I_F: Forward current
V_F: Forward voltage

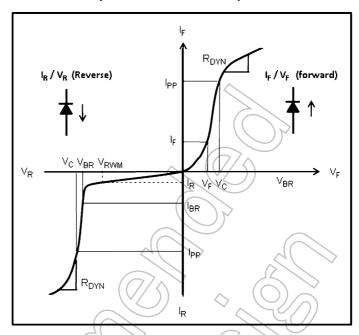


Fig. 5.1 Definitions of Electrical Characteristics

Characteristics	Symbol	Note	Test Condition	Min	Тур.	Max	Unit
Working peak reverse voltage	V_{RWM}))—	-	5.0	V
Reverse breakdown voltage	V _{BR(1)}	7	I _{BR} = 5 mA (between I/O and GND)	6.0	l		V
	V _{BR(2)}		I _{BR} = 5 mA (between V _{BUS} and GND)	6.8			V
Reverse current	I _{R(1)}		V _{RWM} = 5 V (between I/O and GND)	_		0.5	μА
	I _{R(2)}		V _{RWM} = 5 V (between V _{BUS} and GND)	_		0.5	μΑ
Clamp voltage	V _{C(1)}	(Note 1)	I _{PP} = 1 A (between I/O and GND)	_	15	20	V
	V _{C(2)}	(Note 1)	I _{PP} = 2.5 A (between I/O and GND)	_	18	24	٧
	V _{C(3)}	(Note 1)	I _{PP} = 1 A (between V _{BUS} and GND)	_	14	19	٧
	V _{C(4)}	(Note 1)	I _{PP} = 9 A (between V _{BUS} and GND)	_	25	30	٧
Dynamic resistance	R _{DYN(1)}	(Note 2)	(between I/O and GND)	_	0.9		Ω
\wedge (())	R _{DYN(2)}	(Note 2)	(between V _{BUS} and GND)	_	0.6		Ω
Total capacitance	C _{t(1)}	(Note 3)	V _R = 0 V, f = 1 MHz (between I/O and GND)	_	0.6	1.0	pF
	C _{t(2)}		$V_R = 0 \text{ V, f} = 1 \text{ MHz}$ (between V_{BUS} and GND)	_	67	_	pF
\rightarrow	C _{t(3)}		V _R = 0 V, f = 1 MHz (between I/O and I/O)		0.3	_	pF
Input/output-to-ground capacitance difference	$\Delta C_{t ext{-GND}}$		V _R = 0 V, f = 1 MHz (between I/O and GND)	_	0.01	_	pF

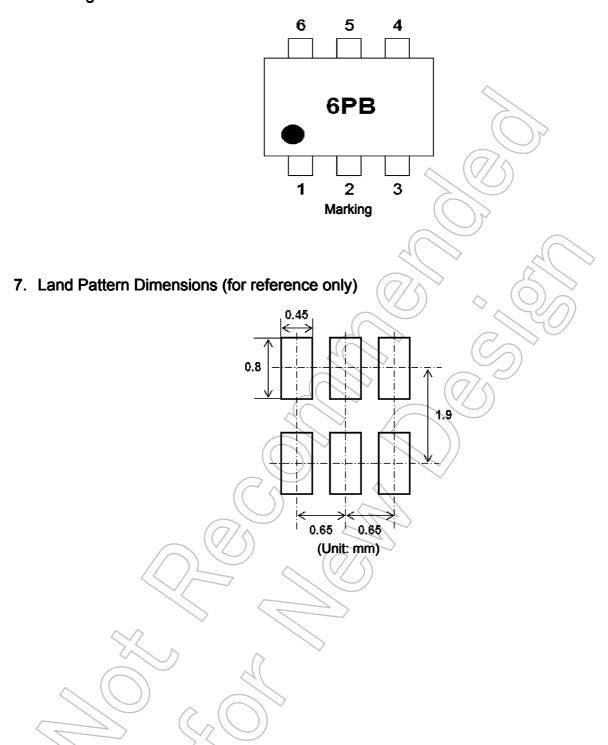
Note 1: Based on IEC61000-4-5 8/20 μ s pulse.

Note 3: Guaranteed by design.

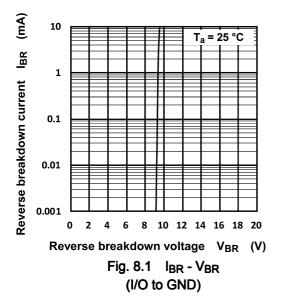
Note 2: TLP parameter: $Z0 = 50 \Omega$, tp = 100 ns, tr = 300 ps, averaging window: t1 = 30 ns to t2 = 60 ns, extraction of dynamic resistance using a least-squares fit of TLP characteristics at I_{PP} between 3 A to 8 A.

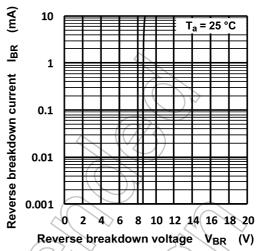


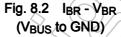
6. Marking

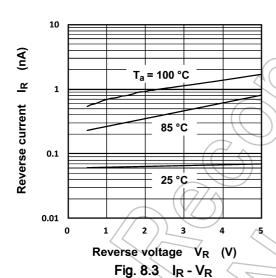


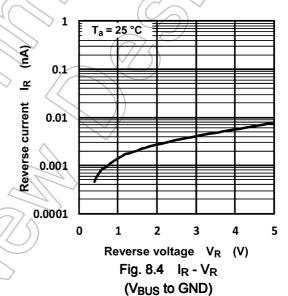
8. Characteristics Curves (Note)



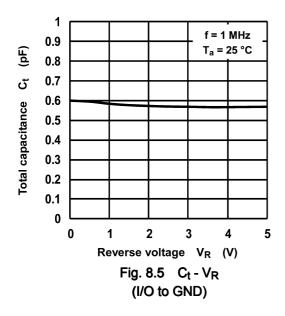


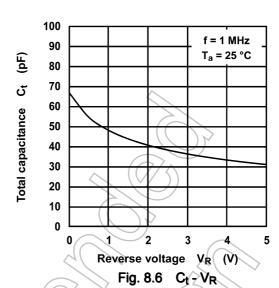




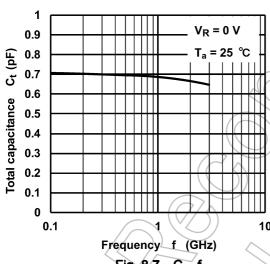


(I/O to GND)





(V_{BUS} to GND)



10 Fig. 8.7 Ct - f (I/O to GND)

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

9. Clamp Voltage V_C - Peak Pulse Current (I_{PP}) (Note)

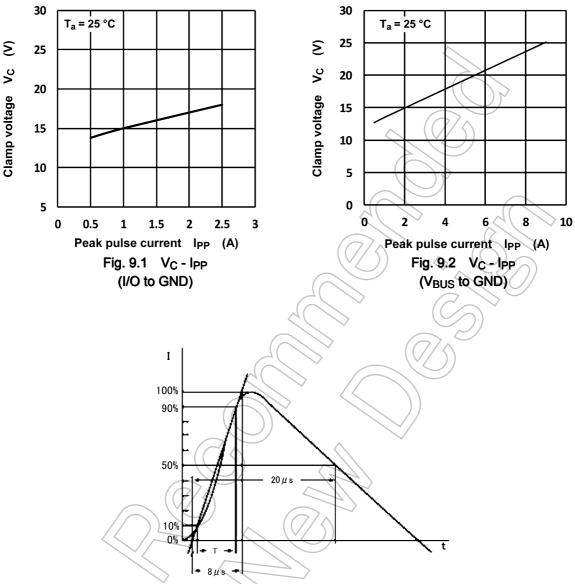
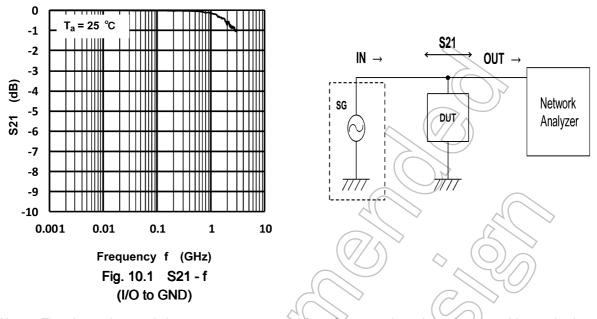


Fig. 9.3 Based on IEC61000-4-5 8/20 μs pulse

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

10. Insertion Loss (S21) (Note)



Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



11. ESD Clamp Waveform (Note)

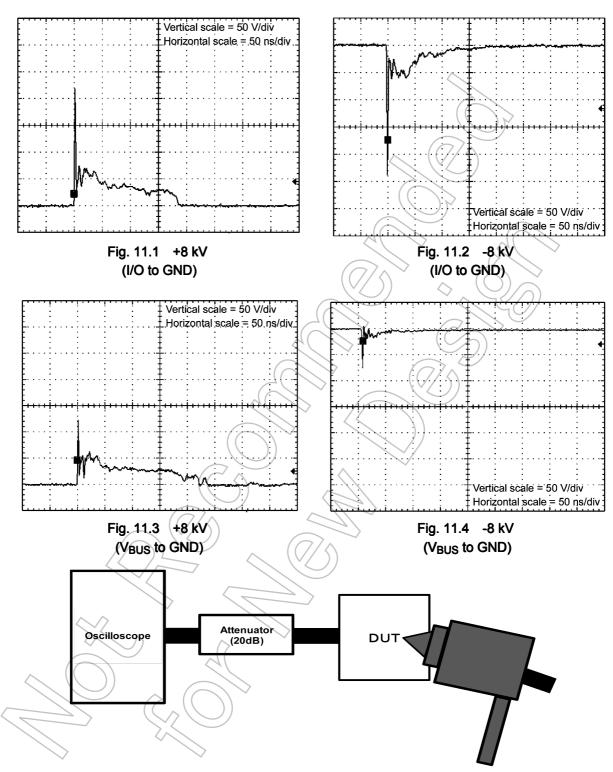


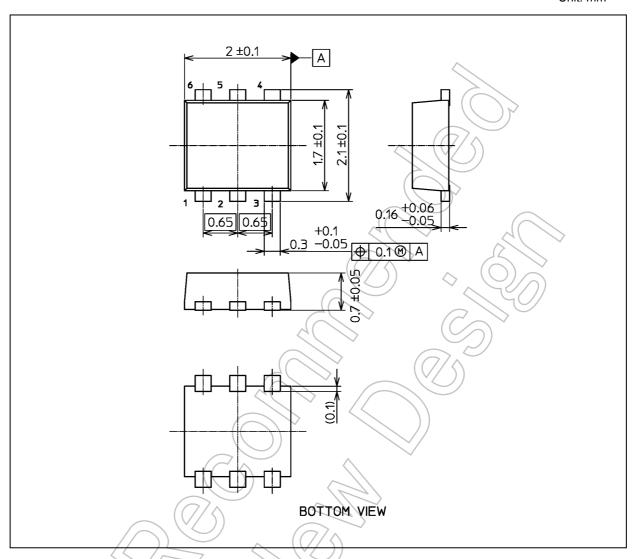
Fig. 11.5 IEC61000-4-2 (Contact)

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

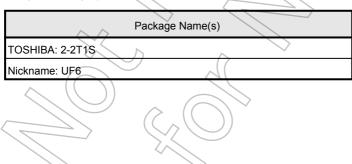


Package Dimensions

Unit: mm



Weight: 7.0 mg (typ.)





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